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REMARKS

The application has been reviewed in light of the Office Action dated October 11, 2007. Claims 1-6, 8, 9, and 11-13 were pending, with claims 7, 10 and 14-32 having previously been canceled, without prejudice or disclaimer. By this Amendment, claims 1, 9 and 13 have been amended to clarify the claimed subject matter, claims 5 and 6 have been canceled, without prejudice or disclaimer, and new claims 33-37 have been added. Accordingly, claims 1-4, 8, 9, 11-13 and 33-37 are now pending, with claims 1, 36 and 37 being in independent form.

Claims 1-6, 8, 9 and 11-13 were rejected under 35 U.S.C. § 102(b) as purportedly anticipated by U.S. Patent No. 6,338,545 (Sekiya '545).

Applicant has carefully considered the Examiner's comments and the cited art, and respectfully submits that independent claims 1, 36 and 37 are patentable over the cited art, for at least the following reasons.

This application relates to a solution jet type fabrication apparatus devised by applicant for forming a wiring pattern on a device substrate by utilizing a jet unit that ejects droplets of a solution containing conductive fine particles onto the substrate.

Sekiya '545 is directed to an apparatus devised by applicant for performing liquid jet recording onto a medium (such as paper) by jetting ink droplets onto the recording paper.

Applicant does not find disclosure or suggestion in Sekiya '545 of various aspect of the solution jet type fabrication apparatus of claim 1 of the present application.

For example, Applicant does not find disclosure or suggestion in Sekiya '545 of a solution jet type fabrication apparatus comprising a holder configured to hold a substrate horizontally to allow a wiring pattern or a device to be formed on said substrate. Each of independent claims 1, 36 and 37 of the present application addresses such features, as well as

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other features.

As another example, Applicant does not find disclosure or suggestion in Sekiya '545 of a solution jet type fabrication apparatus of a configuration that enables forming conductive fine particles of a size equal to or greater than  $0.0005\ \mu\text{m}$  for stable dispersion.

Accordingly, for at least the above-stated reasons, Applicant respectfully submits that independent claims 1, 36 and 37, and the claims depending therefrom, are patentable over the cited art.

In view of the remarks hereinabove, Applicant submits that the application is now in condition for allowance, and earnestly solicits the allowance of the application.

If a petition for an extension of time is required to make this response timely, this paper should be considered to be such a petition. The Patent Office is hereby authorized to charge any fees that are required in connection with this amendment and to credit any overpayment to our Deposit Account No. 03-3125.

If a telephone interview could advance the prosecution of this application, the Examiner is respectfully requested to call the undersigned attorney.

Respectfully submitted,



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